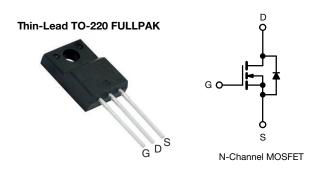
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} max (Ω). at 25 °C	V _{GS} = 10 V 0.18			
Q _g max. (nC)	86			
Q _{gs} (nC)	11			
Q _{gd} (nC)	24			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-Intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer
 - Adaptors
 - Televisions
 - Game console
- Computing
 - Adaptors
 - ATX power supply

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA22N60E-E3
Lead (Pb)-free and halogen-free	SiHA22N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V _{DS}	600	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain surrent (T = 150 °C) e	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	8	
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	T _C = 100 °C		5	Α
Pulsed drain current ^a			I _{DM}	56	
Linear derating factor				0.28	W/°C
Single pulse avalanche energy b			E _{AS}	367	mJ
Maximum power dissipation			P_{D}	35	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dV/dt	70	V/ns	
Reverse diode dV/dt ^d			11	1 v/ns	
Soldering recommendations (peak temperature) c	for 10 s			300	°C
Mounting torque	M3 screw			0.6	Nm

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.1 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	3.6	C/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 250 μA	-	0.71	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Onto anima lankana		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}		V _{GS} = ± 30 V	-	=.	± 1	μΑ
Zoro goto voltago droin ourrent	1	V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	^
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.15	0.18	Ω
Forward transconductance	9 _{fs}	V _D	_S = 8 V, I _D = 5 A	-	6.4	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	1920	-	pF
Output capacitance	C _{oss}	7	$V_{DS} = 0.0$, $V_{DS} = 100 \text{ V}$,		90	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	73	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	263	-	
Total gate charge	Qg			-	57	86	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 11 A, V_{DS} = 480 V$	-	11	-	nC
Gate-drain charge	Q _{gd}			-	24	-	
Turn-on delay time	t _{d(on)}			-	18	36	
Rise time	t _r	V _{DD} = 380 V, I _D = 11 A,		-	27	54	1
Turn-off delay time	t _{d(off)}		$V_{DD} = 380 \text{ V}, I_D = 11 \text{ A},$ $V_{GS} = 10 \text{ V}, R_q = 4.7 \Omega$		66	99	ns
Fall time	t _f		J	-	35	70	
Gate input resistance	R_g	f = 1 MHz, open drain		0.3	0.77	1.2	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed diode forward current	I _{SM}			-	-	56	A
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 11 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}			-	344	-	ns
Reverse recovery charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 11 A, dI/dt = 100 A/μs, V _R = 25 V		-	5.3	-	μC
Reverse recovery current	I _{RRM}			-	28	-	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

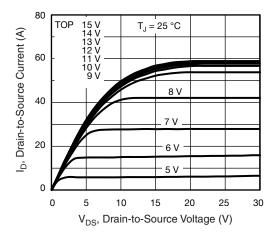


Fig. 1 - Typical Output Characteristics

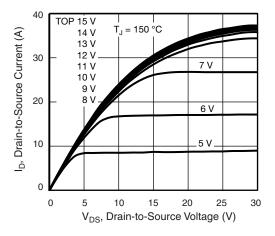


Fig. 2 - Typical Output Characteristics

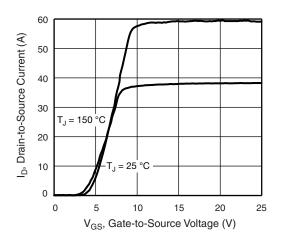


Fig. 3 - Typical Transfer Characteristics

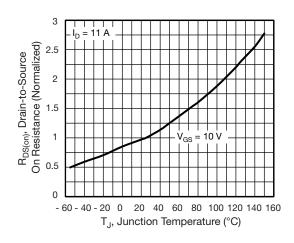


Fig. 4 - Normalized On-Resistance vs. Temperature

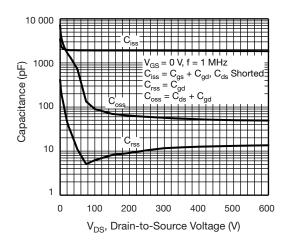


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

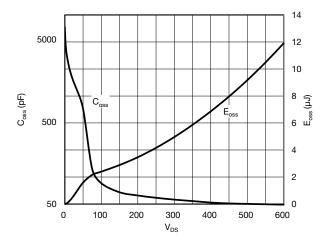


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



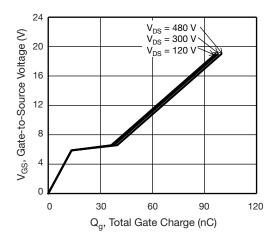


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

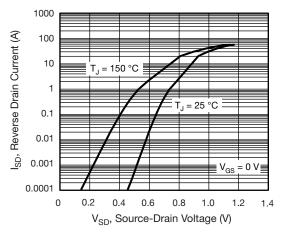


Fig. 8 - Typical Source-Drain Diode Forward Voltage

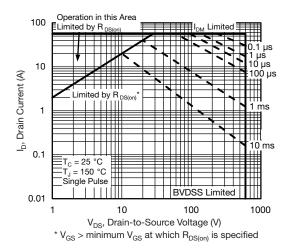


Fig. 9 - Maximum Safe Operating Area

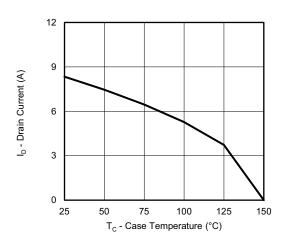


Fig. 10 - Maximum Drain Current vs. Case Temperature

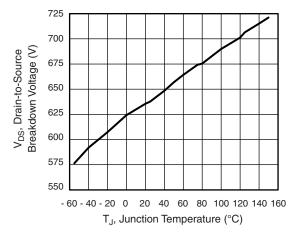


Fig. 11 - Temperature vs. Drain-to-Source Voltage



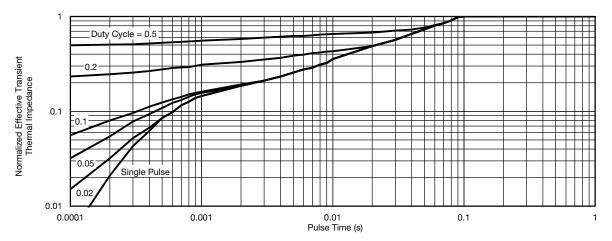


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

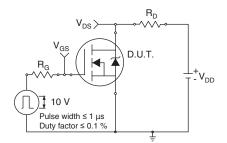


Fig. 13 - Switching Time Test Circuit

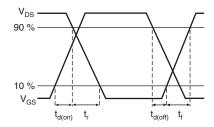


Fig. 14 - Switching Time Waveforms

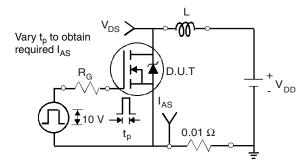


Fig. 15 - Unclamped Inductive Test Circuit

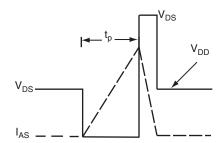


Fig. 16 - Unclamped Inductive Waveforms

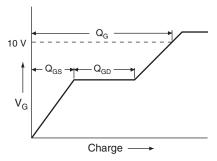


Fig. 17 - Basic Gate Charge Waveform

Current regulator Same type as D.U.T D.U.T. V_{GS} >

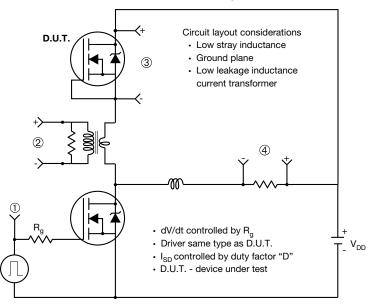
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Fig. 18 - Gate Charge Test Circuit

Current sampling resistors



Peak Diode Recovery dV/dt Test Circuit



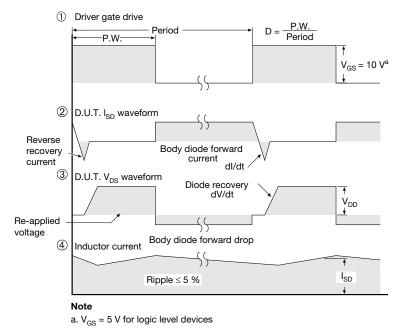


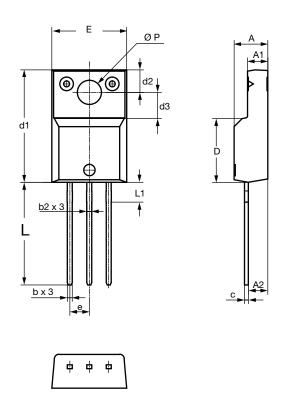
Fig. 19 - For N-Channel

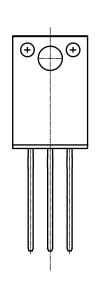
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TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS	
	MILLIM	IETERS	INCH	S
	MIN.	MAX.	MIN.	MAX.
А	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
E	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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